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Appts. for fabricating semiconductor devices - including a gas discharge pipe connected to sealing door where devices are charged and discharged
Patent Assignee: NEC YAMAGATA LTD

Patent Family

| Patent Number | Kind | Date | Application Number | Kind | Date | Week | Type |
|---------------|------|----------|--------------------|------|----------|--------|------|
| JP 5251426 | A | 19930928 | JP 9246524 | A | 19920304 | 199343 | B |

Priority Applications (Number Kind Date): JP 9246524 A (19920304)

Patent Details

| Patent | Kind | Language | Page | Main IPC | Filing Notes |
|------------|------|----------|------|-------------|--------------|
| JP 5251426 | A | | 3 | H01L-021/31 | |

Abstract:

JP 5251426 A

Appts. comprises a gas discharge pipe connected to the sealing door provided at the side where semiconductor devices are charged and discharged.

USE - Used for depositing oxide films, nitride films, etc. under low pressure.

Dwg.1/2

Derwent World Patents Index

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